

SOT1123-2

plastic thermal enhanced ball grid array package; 324 balls;
heatsink

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HBGA324
Package type industry code	HBGA324
Package style descriptive code	HBGA (thermal enhanced ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	144E
JEDEC package outline code	MS-034
JEITA package outline code	- - -
Mounting method type	S (surface mount)
Issue date	6-1-2010

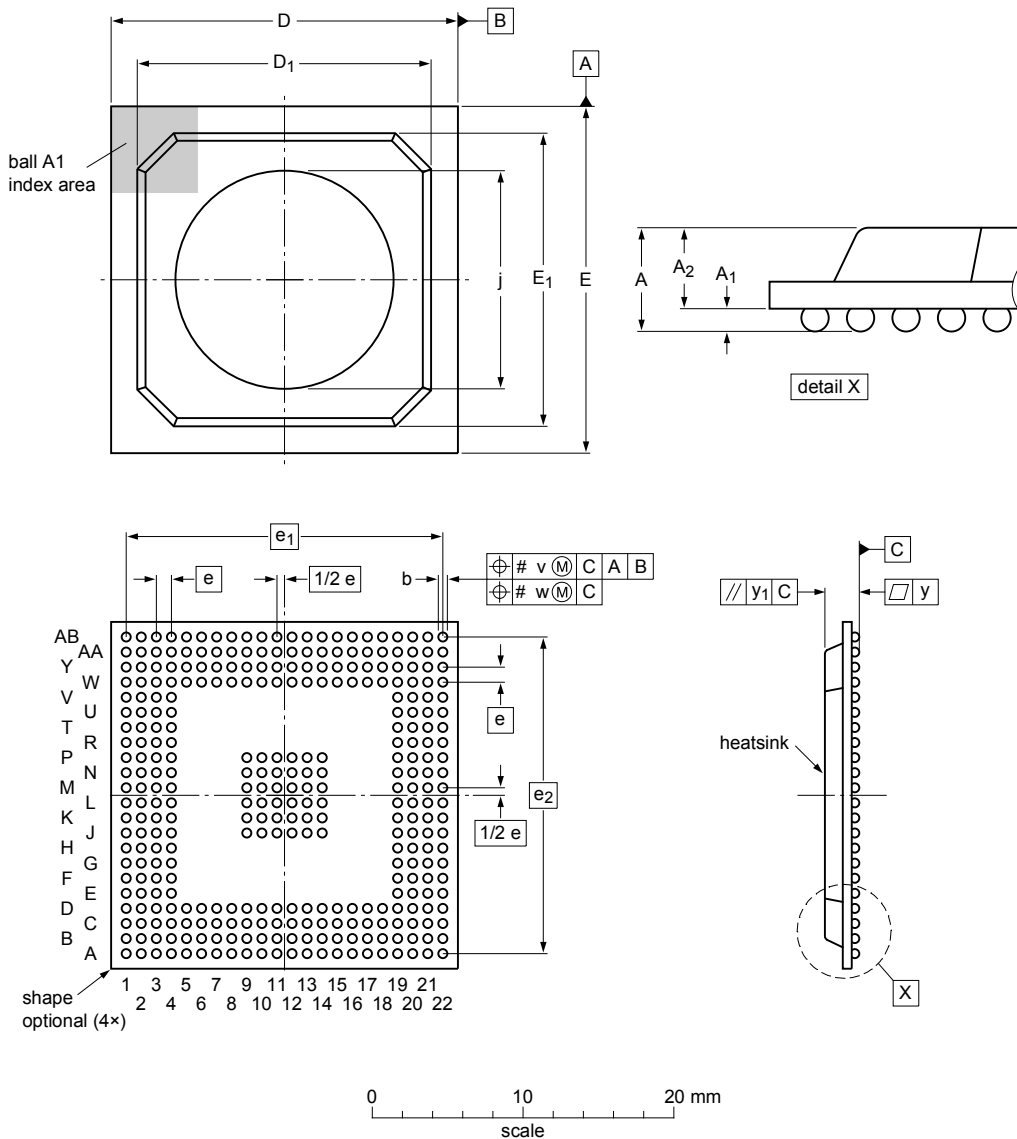
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	22.8	-	23	23.2	mm
E	package width	22.8	-	23	23.2	mm
A	seated height	2	-	2.23	2.45	mm
A ₂	package height	1.6	-	1.73	1.85	mm
e	nominal pitch	-	-	1	-	mm
n ₂	actual quantity of termination	-	-	324	-	



2. Package outline

HBGA324: plastic thermal enhanced ball grid array package; 324 balls; heatsink SOT1123-2



Dimensions

Unit	A	A ₁	A ₂	b	D	D ₁	E	E ₁	e	e ₁	e ₂	j	v	w	y	y ₁
max	2.45	0.6	1.85	0.7	23.2	20.75	23.2	20.75				15.7				
mm nom	2.23	0.5	1.73	0.6	23.0	20.00	23.0	20.00	1	21	21	15.2	0.25	0.1	0.2	0.35
min	2.00	0.4	1.60	0.5	22.8	19.75	22.8	19.75				14.7				

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1123-2	144E	MS-034	---		09-11-18 10-01-06

Fig. 1. Package outline HBGA324 (SOT1123-2)

3. Legal information

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